L Number	Hits	Search Text	DB	Time stamp
1	27	438/689.ccls. and ball\$2	USPAT;	2003/01/15 10:40
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		,	IBM_TDB	
2	20789	wafer near (remov\$3 or thin\$4 or etch\$3)	USPAT;	2003/01/15 10:59
			US-PGPUB;	
]			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
3	6724	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/01/15 11:07
		and (glass or holder)	US-PGPUB;	
			EPO; JPO;	
		,	DERWENT;	
1	4257	(water near (remarks or thinks or etches))	IBM_TDB	2002/01/15 11:00
4	4257	<pre>(wafer near (remov\$3 or thin\$4 or etch\$3)) and ((glass or holder) with (wafer or</pre>	USPAT; US-PGPUB;	2003/01/15 11:08
		silicon))	EPO; JPO;	
		51110011//	DERWENT;	
			IBM TDB	
5	2407	((wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 11:10
		and ((glass or holder) with (wafer or	US-PGPUB;	
		silicon))) and (via or trench or cavity)	EPO; JPO;	
		-	DERWENT;	
			IBM_TDB	
6	342		USPAT;	2003/01/15 12:59
		and ((glass or holder) with (wafer or	US-PGPUB;	
		silicon))) and (via or trench or cavity))	EPO; JPO;	
		and ball\$2	DERWENT;	
_		, , , , , , , , , , , , , , , , , , , ,	IBM_TDB	
7	8198	(wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 11:07
		and (glass or holder or chuck)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
8	5782	((wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 11:08
~	3,02	and (glass or holder or chuck)) and ((glass	US-PGPUB;	2003,01,13 11.00
		or holder or chuck) with (wafer or silicon))	EPO; JPO;	
		, , , , , , , , , , , , , , , , , , , ,	DERWENT;	
			IBM TDB	
9	3184	(((wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 11:10
		and (glass or holder or chuck)) and ((glass	US-PGPUB;	
]		or holder or chuck) with (wafer or	EPO; JPO;	
		silicon))) and (via or trench or cavity)	DERWENT;	
1			IBM_TDB	
10	477	1	USPAT;	2003/01/15 11:11
]		etch\$3)) and (glass or holder or chuck))	US-PGPUB;	
		and ((glass or holder or chuck) with (wafer	EPO; JPO;	
		or silicon))) and (via or trench or cavity)) and ball\$2	DERWENT;	
11	392	·	IBM_TDB USPAT;	2002/01/15 12:00
	392	etch\$3)) and (glass or holder or chuck))	US-PGPUB;	2003/01/15 12:06
		and ((glass or holder or chuck) with (wafer	EPO; JPO;	
		or silicon))) and (via or trench or cavity))	DERWENT;	
ĺ		and ball\$2) and (@ad<20010531)	IBM_TDB	
	·	· · · · · · · · · · · · · · · · · · ·		

12	92	("3739463" "3810129" "3811117"	USPAT	2003/01/15 11:28
		"3838501" "3881884" "3991296"		,
		"3993917"		
		"4368106"		
		"4467518" "4603341" "4612083"		
		"4628174"		
		"4769738" "4807021" "4822755"		
		"4842699" "4897708" "4954458"		
		"4978639" "4996587" "5024970"		
		"5064771"		
		"5160987" "5166097" "5191405"		
		"5225771" "5259924" "5268326"		
		"5270261" "5307942" "5309318"		
1		"5313097" "5314844" "5322816"		
		"5323035" "5340771" "5380681"		
		"5399898" "5414637" "5426566"		
		"5453404" "5463246" "5466634"		
		"5467305" "5468663" "5472914"		
		"5478781" "5489554" "5494832"		
		"5502333" "5502667" "5504036"		
		"5506753" "5517057" "5517754"		
		"5532519" "5550942" "5561622"		:
		"5563086" "5567653" "5567654"		
		"5571754" "5596226" "5627106"		
		"5646067" "5654127" "5656553"		
		"5691248" "5707485" "5766984"		
		"5824595" "5843844" "5846879"	•	
		"5851845" "5888882" "5888883"		
		"5979475" "5998292" "6004867"		
		"6083811" "6121119" "6162701"		
	_	"6176966" "6184060").PN.		
13	5	("5024970" "5223450" "5270261"	USPAT	2003/01/15 11:32
		"5346848" "5691248").PN.		
14	13	6004867.URPN.	USPAT	2003/01/15 11:32
15	4	("3508980" "4839309" "5013681"	USPAT	2003/01/15 11:37
1		"5091330").PN.		
18	41	5071792.URPN.	USPAT	2003/01/15 11:40
19	11	5903044.URPN.	USPAT	2003/01/15 11:59
21	336		USPAT;	2003/01/15 12:39
			US-PGPUB;	
			EPO; JPO;	•
			DERWENT;	
22	710	(water near (removed) on thinks on about 2)	IBM_TDB	2002/01/15 10 20
22	712	(wafer near (remov\$3 or thin\$4 or etch\$3))	USPAT;	2003/01/15 12:38
		and ((back near etch) or beol)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
23	668	(water near (removed on thinks on about 2))	IBM_TDB	2222/21/15 12 22
23	668	<pre>(wafer near (remov\$3 or thin\$4 or etch\$3)) and ((back near etch))</pre>	USPAT;	2003/01/15 12:39
		and ((back hear etch))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
24	593	((wafer near (remov\$3 or thin\$4 or etch\$3))	IBM_TDB	2002/01/15 12 52
24	393	and ((back near etch))) and (@ad<20010531)	USPAT;	2003/01/15 12:52
		and (back near ecch)) and (wad<20010531)	US-PGPUB;	
[İ		EPO; JPO;	
			DERWENT;	
25	490	((wafer near (removed or thine) or otabea))	IBM_TDB	2002/01/15 12 52
23	430	<pre>(((wafer near (remov\$3 or thin\$4 or etch\$3)) and ((back near etch))) and (@ad<20010531))</pre>	USPAT; US-PGPUB;	2003/01/15 12:50
		and (chip or die or package or ball\$2 or via		
		or trench or groove or cavity)	EPO; JPO; DERWENT;	
		or eremen or groove or cavity)	IBM TDB	
26	o	(wafer near ball\$2) and ((trench or groove	–	2002/01/15 12:52
20	٦	or cavity) near wafer)	USPAT; US-PGPUB;	2003/01/15 12:52
		or outlog, hour wardly	EPO; JPO;	
			DERWENT;	
			IBM TDB	
L			מחז הום ד	

27	109	(wafer near ball\$2)	USPAT;	2003/01/15 12:52
			US-PGPUB;	, , , , , , , , , , , , , , , , , , , ,
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
28	92	((wafer near ball\$2)) and (@ad<20010531)	USPAT;	2003/01/15 12:59
			US-PGPUB;	, ,
			EPO; JPO;]
	1		DERWENT;	
			IBM TDB	
29	135	438/For.403.ccls.	USPAT;	2003/01/15 13:04
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
30	135	438/For.403.ccls. and (@ad<20010531)	USPAT;	2003/01/15 13:05
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
31	13	438/For.403.ccls. and (ball\$s or contact or	USPAT;	2003/01/15 13:04
		interconnect\$3)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
32	468	438/977.ccls.	USPAT;	2003/01/15 13:04
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
33	319	,	USPAT;	2003/01/15 13:04
		interconnect\$3)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
34	314	(438/977.ccls. and (ball\$s or contact or	USPAT;	2003/01/15 13:05
		interconnect\$3)) and (@ad<20010531)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	